Coatless™ Sn Strip

Is a single-step, liquid stripping agent that removes solder coatings, tin and tin-copper alloys. Formulated to strip printed wiring boards with minimal attack on the copper substrate. Copper is revealed to be bright, even and shiny. Coatless™ Sn Strip is used at room temperature to save on heating costs. It was designed free of fluorides, fluoroborates, and peroxide with no complex chelators resulting in simple waste treatment and cost saving.

Features/Benefits

- Fast stripping time
- No sludge build-up in the tank
- Leaves copper substrate bright and even
- Single step, ready-to-use solution
- Easy control

Equipment

Polypropylene or polyethylene tanks are to be used. Good ventilation is needed to keep exposure under limits.

Operating Conditions

Concentration	Used as is
Temperature	20-28 °C

Maintenance

Solution needs to be replaced once the stripping time is too long for normal operation. The solution rises in temperature depending on the throughput of the operation. Maintain the temperature within recommended range.

The data and statements contained in this bulletin are based on testing information and are believed to be accurate and reliable. This bulletin is not a Guarantee or Warranty, express or implied regarding the products use. The product is sold on the condition that the purchaser will do their own tests to determine the suitability of the product in a particular application.

READ THE SDS BEFORE USING THIS PRODUCT